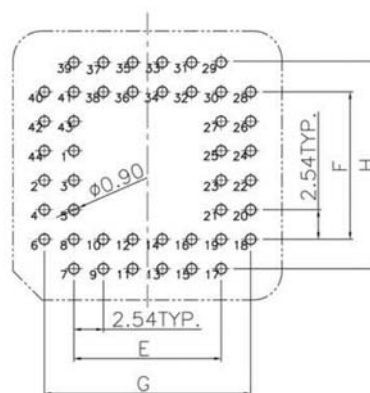
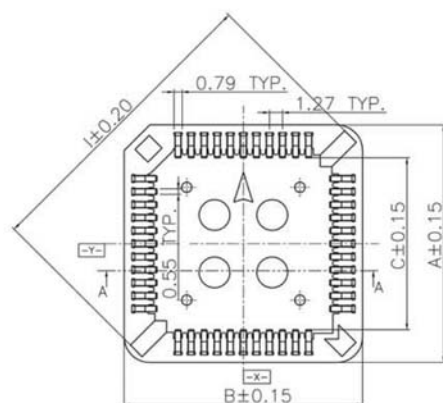
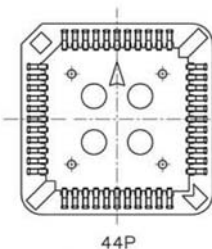
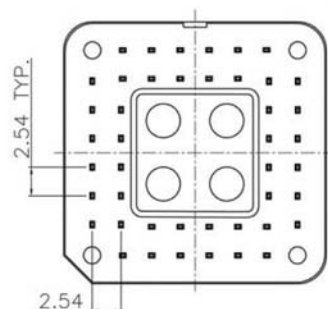
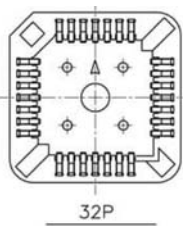
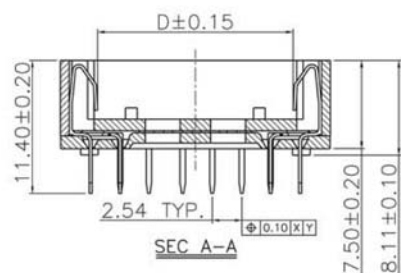




RECOMMENDED P.C. BOARD LAYOUT



Dimension No. Of Pin	A	B	C	D	E	F	G	H	I
DIP – 20P	15.56	15.56	9.10	9.10	5.08	5.08	10.16	10.16	17.55
DIP – 28P	18.10	18.10	11.66	11.66	7.62	7.62	12.70	12.70	21.25
DIP – 32P	20.60	18.10	14.17	11.69	7.62	10.16	12.70	15.24	23.00
DIP – 44P	23.48	23.48	16.78	16.78	12.70	12.70	17.78	17.78	28.50
DIP – 52P	25.88	25.88	19.28	19.28	15.24	15.24	20.32	20.32	32.45
DIP – 68P	31.66	31.66	24.35	24.35	20.32	20.32	25.40	25.40	39.30
DIP – 84P	36.66	36.66	29.38	29.38	25.40	25.40	30.48	30.48	46.85

NOTES:
SPECIFICATIONS:
CURRENT RATING:1 AMP.
VOLTAGE:250V AC/DC MAX.
DIELECTRIC WITHSTANDING:500VAC FOR ONE MINUTE.
CONTACT RESISTANCE:30mΩ (MAX).
INSULATION RESISTANCE:1000MΩ (MIN).
OPERATING TEMPERATURE:-55°C+105°C
RETENTION FORCE:0.30KG PER PIN (MIN).
MATERIALS:
BODY: PBT+30%GF UL 94V-0.
COVER:PBT+30%GF UL 94V-0.
CONTACTS:PHOSOR BRONZE.
CONTACT PLATING TIN/GOLD.

Scale	1:1							Name
TOLERANCE						Drawn	11.07.11	Chappel
X.X	±0.40					Approved		
X.XX	±0.25							
X.XXX	±0.15							
Angle	±3°					 		
			Modification	Date	Name			

Item No.	A-CCSxx-Z-R (Tin) A-CCSxx-G-R (Gold)
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Title	Chip-Carrier PLCC socket, 2.54MM pitch
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Drawing No.

rev00

Replace

	Sheet
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